

Leading UK Manufacturer of Solder Paste, Solid & Cored Solder Wires, Lead Free & Rosin Free Solders, Fluxes, Cleaners and High Purity Bar Solder Products.

TECHNICAL DATA SHEET



No Clean Lead Free Solder Paste

Description

Microprint P2010 is a no clean, lead free solder paste for air and nitrogen reflow. It has been developed to work well at higher processing temperatures as required by the SAC alloys and is available in Type 3, 4 and 5 powder size. Microprint P2010 is suitable for a variety of substrate materials including Sn/Pb, Au/Ni and OSP treat finishes.

Benefits

- Fast print: 20-100mm/sec
- No clean: ROM0 (J-STD-004)
- Halogen free
- Slump free / No solder balling
- Suitable for air / nitrogen
- Clear probe testable residue
- Excellent soldering / 72 hour tack life
- 12 months refrigerated shelf life (stored at <10°C)

Cleaning

Residues can be easily removed using Warton's Total Clean and Surf Clean range of cleaners. For stencil cleaning use Warton's Total Clean 130.

Storage Conditions

Microprint P2010 can be stored at room temperature, however storage in a refrigerator will prolong life.

Shelf Life

Microprint P2010 has a shelf life of 12 months for unopened containers stored at <10°C

Availability

Warton Metals manufacture all solder paste in the UK.

Alloy	Metals	Particle Size	Packaging
SAC305	88.5%	25-45 μm (T3)	1000 g, 500 g Cartridges, 1000 g, 500 g, 250 g Tubs
SAC305	88.5%	20-38 μm (T4)	1000 g, 500 g Cartridges, 1000 g, 500 g, 250 g Tubs
SAC305	88.5%	15-32 μm	1000 g, 500 g Cartridges, 1000 g, 500 g, 250 g Tubs
SAC305	88.0%	25-45 μm (T3)	40 g, 75 g automated / manual syringes





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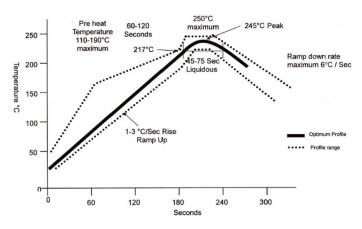
Printing

Ensure the paste is at room temperature before opening. For tubs, stir and apply sufficient paste to the stencil to allow for an even roll whilst printing. Microprint P2010 is suitable for printing speeds between 20-100 mm/sec.

Reflow

Microprint P2010 is suitable for all reflow technologies.

The reflow profile for Sn, Ag, Cu (SAC) pastes using vapour phase reflow oven activation temperature range 140°C-170°C, peak temperature is 230°C-245°C.







Commitment to Care

Lead free soldering represents a clear commitment to care for the long-term health of our planet and its inhabitants, by eliminating the use of toxic materials which can leech into the water supply. Microprint P2010 Solder Paste is formulated without the use of toxic metals such as Lead, Antimony or Nickel. Warton Metals offers a commitment to care for users of Microprint Solder Pastes and Warton Metals insistence on ethical product development allows you to fulfil your commitment to the environment and manufacturing performance whilst offering you peace of mind.

The information supplied in this technical data sheet is designed only as guidance for the safe use and handling of the product. This information is correct to the best of our knowledge and belief at the date of publication however no guarantee is made to its accuracy. This information related only to the specific material designated and may not be valid for such material used in combination with any other materials or in any other process (2020).

